THE DATASHEET OF

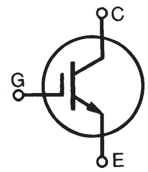
IXGH50N60C4

High-Gain IGBTs

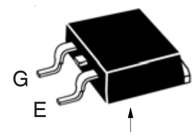
IXGA50N60C4
IXGP50N60C4
IXGH50N60C4

V_{CES} = 600V
I_{C110} = 46A
$V_{CE(sat)}$ ≤ 2.3V

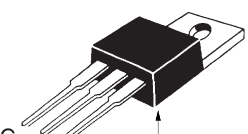
High-Speed PT Trench IGBT



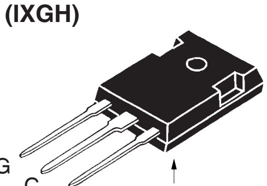
TO-263 AA (IXGA)



TO-220AB (IXGP)



TO-247 (IXGH)



G = Gate　　D = Collector
S = Emitter　　Tab = Collector

Symbol	Test Conditions	Maximum Ratings	
V_{CES}	T_J = 25°C to 150°C	600	V
V_{CGR}	T_J = 25°C to 150°C, R_{GE} = 1MΩ	600	V
V_{GES}	Continuous	±20	V
V_{GEM}	Transient	±30	V
I_{C25}	T_C = 25°C	90	A
I_{C110}	T_C = 110°C	46	A
I_{CM}	T_C = 25°C, 1ms	220	A
SSOA (RBSOA)	V_{GE} = 15V, T_{VJ} = 125°C, R_G = 10Ω Clamped Inductive Load	I_{CM} = 72 $V_{CE} \leq V_{CES}$	A
P_C	T_C = 25°C	300	W
T_J		-55 ... +150	°C
T_{JM}		150	°C
T_{stg}		-55 ... +150	°C
T_L	Maximum Lead Temperature for Soldering	300	°C
T_{SOLD}	1.6 mm (0.062in.) from Case for 10s	260	°C
F_C	Mounting Force (TO-263)	10..65 / 2.2..14.6	N/lb.
M_d	Mounting Torque (TO-220 & TO-247)	1.13 / 10	Nm/lb.in.
Weight	TO-263	2.5	g
	TO-220	3.0	g
	TO-247	6.0	g

Symbol	Test Conditions (T_J = 25°C, Unless Otherwise Specified	Characteristic Values Min.	Typ.	Max.	
BV_{CES}	I_C = 250μA, V_{GE} = 0V	600			V
$V_{GE(th)}$	I_C = 250μA, V_{CE} = V_{GE}	4.0		6.5	V
I_{CES}	V_{CE} = V_{CES}, V_{GE} = 0V			25	μA
	T_J = 125°C			1	mA
I_{GES}	V_{CE} = 0V, V_{GE} = ±20V			±100	nA
$V_{CE(sat)}$	I_C = 36A, V_{GE} = 15V, Note 1		1.9	2.3	V
	T_J = 125°C		1.6		V

Features

- Optimized for Low Switching Losses
- International Standard Packages
- Square RBSOA

Advantages

- Easy to Mount
- Space Savings

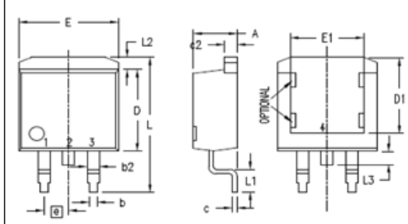
Applications

- Power Inverters
- UPS
- Motor Drives
- SMPS
- PFC Circuits
- Battery Chargers
- Lamp Ballasts

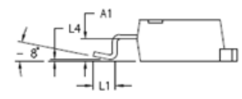
Symbol	Test Conditions (T_J = 25°C Unless Otherwise Specified)	Characteristic Values Min.	Typ.	Max.	
g_{fs}	I_C = 36A, V_{CE} = 10V, Note 1	20	30		S
C_{ies}	V_{CE} = 25V, V_{GE} = 0V, f = 1MHz		1900		pF
C_{oes}			100		pF
C_{res}			60		pF
Q_g	$I_C = I_{C110}$, V_{GE} = 15V, $V_{CE} = 0.5 \bullet V_{CES}$		113		nC
Q_{ge}			13		nC
Q_{gc}			44		nC
$t_{d(on)}$	**Inductive Load, T_J = 25°C**		40		ns
t_{ri}	I_C = 36A, V_{GE} = 15V		66		ns
E_{on}	V_{CE} = 400V, R_G = 10Ω		0.95		mJ
$t_{d(off)}$	Note 2		270		ns
t_{fi}			63		ns
E_{off}			0.84	1.55	mJ
$t_{d(on)}$	**Inductive Load, T_J = 125°C**		30		ns
t_{ri}	I_C = 36A, V_{GE} = 15V		45		ns
E_{on}	V_{CE} = 400V, R_G = 10Ω		1.10		mJ
$t_{d(off)}$	Note 2		210		ns
t_{fi}			96		ns
E_{off}			0.90		mJ
R_{thJC}				0.42	°C/W
R_{thCS}	TO-247		0.21		°C/W
	TO-220		0.50		°C/W

Notes:
1. Pulse test, t ≤ 300μs, duty cycle, d ≤ 2%.
2. Switching times & energy losses may increase for higher V_{CE}(clamp), T_J or R_G.

TO-263 Outline

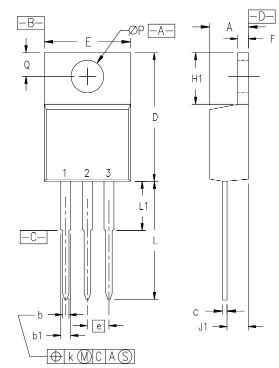


1 = Gate
2 = Collector
3 = Emitter
4 = Collector



SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.160	.190	4.06	4.83
A1	.080	.110	2.03	2.79
b	.020	.039	0.51	0.99
b2	.045	.055	1.14	1.40
c	.016	.029	0.40	0.74
c2	.045	.055	1.14	1.40
D	.340	.380	8.64	9.65
D1	.315	.350	8.00	8.89
E	.380	.410	9.65	10.41
E1	.245	.320	6.22	8.13
e	.100 BSC		2.54 BSC	
L	.575	.625	14.61	15.88
L1	.090	.110	2.29	2.79
L2	.040	.055	1.02	1.40
L3	.050	.070	1.27	1.78
L4	0	.005	0	0.13

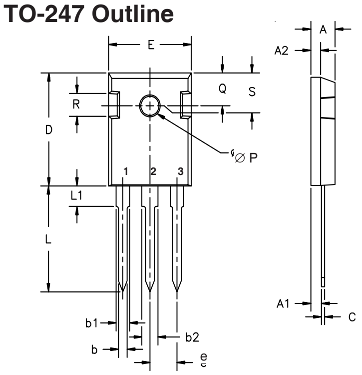
TO-220 Outline



1 = Gate   2 = Collector
3 = Emitter

SYM	INCHES MIN	INCHES MAX	MILLIMETERS MIN	MILLIMETERS MAX
A	.170	.190	4.32	4.83
b	.025	.040	0.64	1.02
b1	.045	.065	1.15	1.65
c	.014	.022	0.35	0.56
D	.580	.630	14.73	16.00
E	.390	.420	9.91	10.66
e	.100 BSC		2.54 BSC	
F	.045	.055	1.14	1.40
H1	.230	.270	5.85	6.85
J1	.090	.110	2.29	2.79
k	0	.015	0	0.38
L	.500	.550	12.70	13.97
L1	.110	.230	2.79	5.84
∅P	.139	.161	3.53	4.08
Q	.100	.125	2.54	3.18

TO-247 Outline



Terminals: 1 - Gate   2 - Collector
3 - Emitter

Dim.	Millimeter Min.	Millimeter Max.	Inches Min.	Inches Max.
A	4.7	5.3	.185	.209
A_1	2.2	2.54	.087	.102
A_2	2.2	2.6	.059	.098
b	1.0	1.4	.040	.055
b_1	1.65	2.13	.065	.084
b_2	2.87	3.12	.113	.123
C	.4	.8	.016	.031
D	20.80	21.46	.819	.845
E	15.75	16.26	.610	.640
e	5.20	5.72	0.205	0.225
L	19.81	20.32	.780	.800
L1		4.50		.177
∅P	3.55	3.65	.140	.144
Q	5.89	6.40	0.232	0.252
R	4.32	5.49	.170	.216
S	6.15 BSC		242 BSC	

IXYS Reserves the Right to Change Limits, Test Conditions, and Dimensions.

Fig. 1. Output Characteristics @ T_J = 25ºC

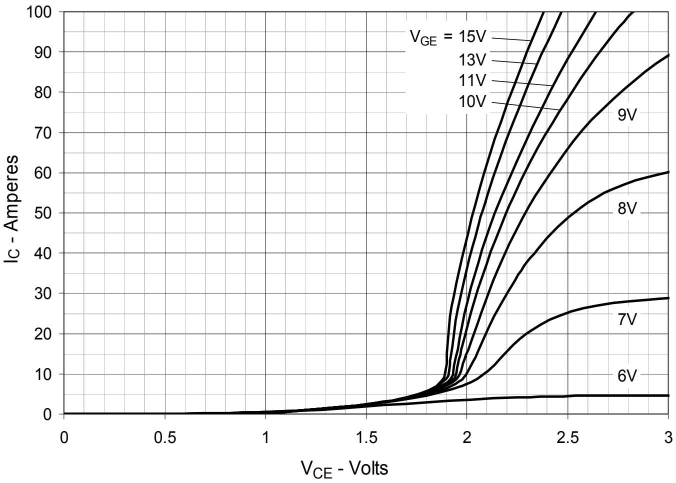


Fig. 2. Extended Output Characteristics @ T_J = 25ºC

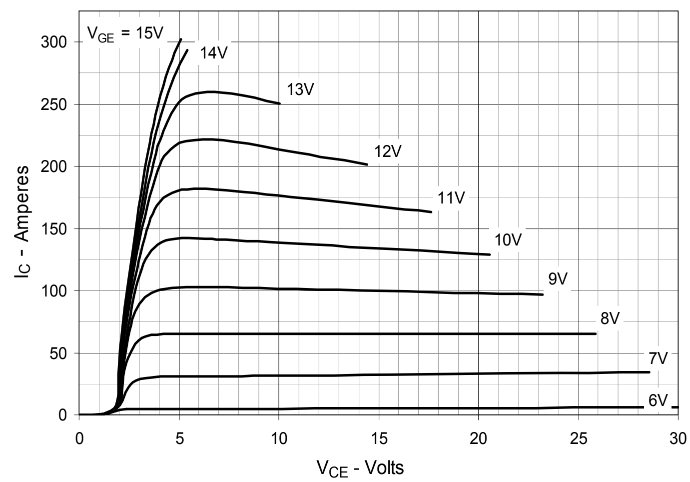


Fig. 3. Output Characteristics @ T_J = 125ºC

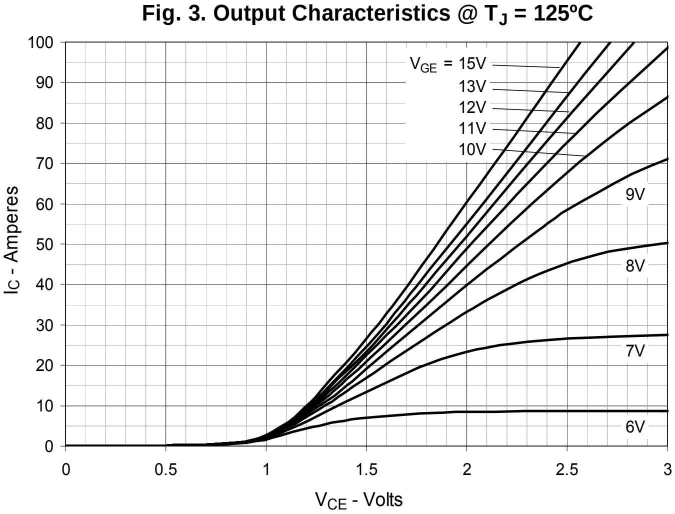


Fig. 4. Dependence of $V_{CE(sat)}$ on Junction Temperature

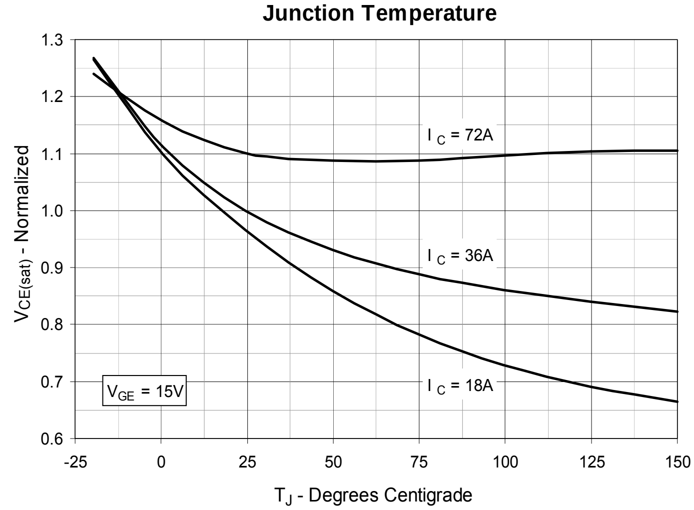


Fig. 5. Collector-to-Emitter Voltage vs. Gate-to-Emitter Voltage

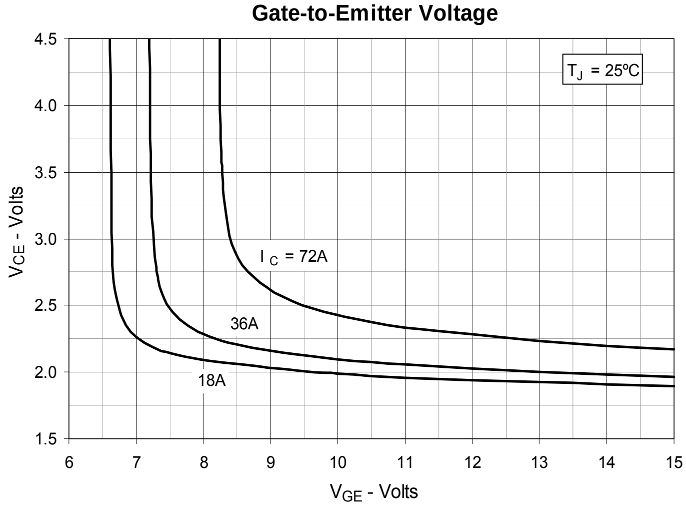
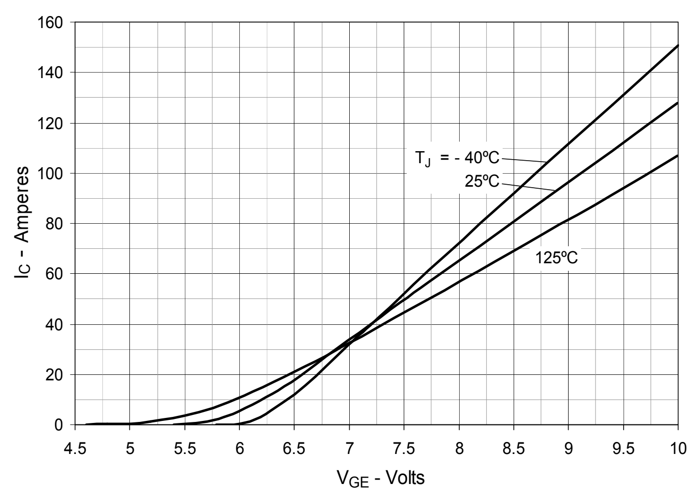


Fig. 6. Input Admittance



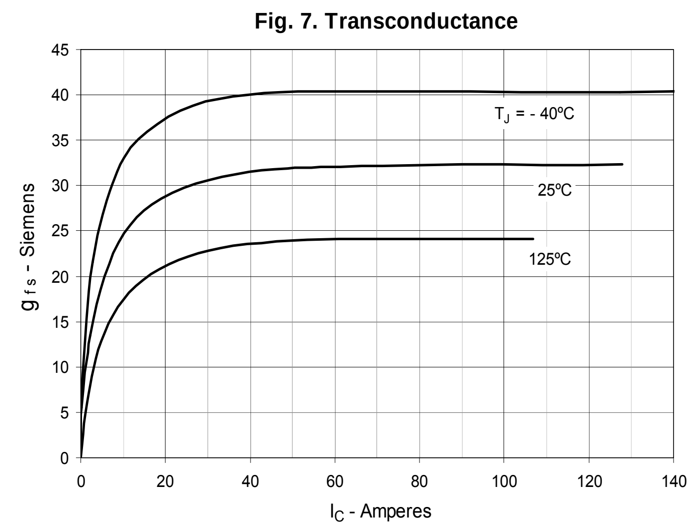


Fig. 7. Transconductance
gfs - Siemens
IC - Amperes
TJ = - 40ºC
25ºC
125ºC

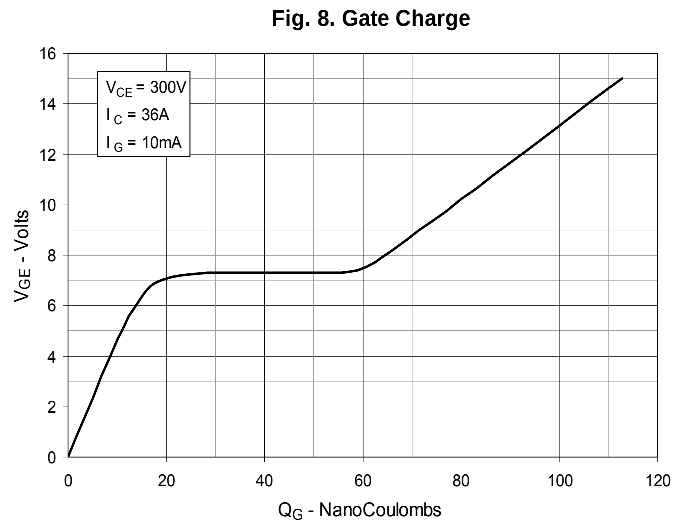


Fig. 8. Gate Charge
VCE = 300V
I C = 36A
I G = 10mA
VGE - Volts
QG - NanoCoulombs

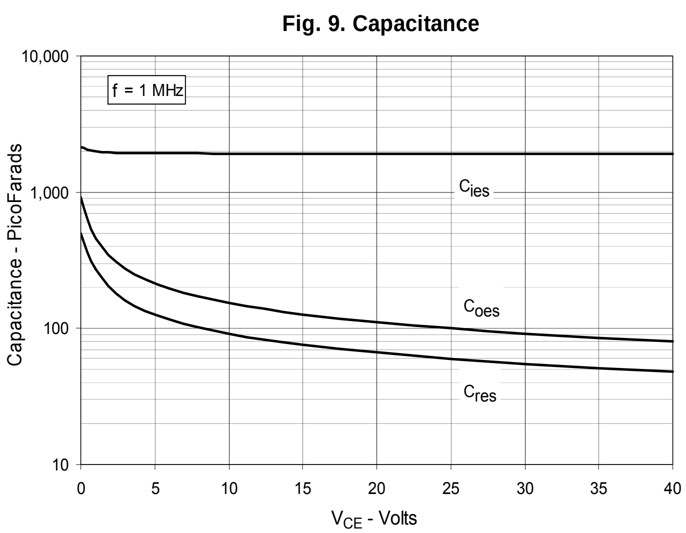


Fig. 9. Capacitance
f = 1 MHz
Cies
Coes
Cres
Capacitance - PicoFarads
VCE - Volts

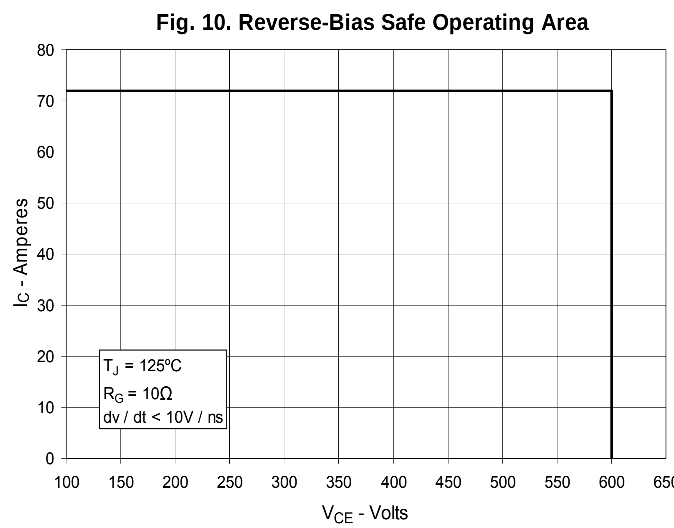


Fig. 10. Reverse-Bias Safe Operating Area
TJ = 125ºC
RG = 10Ω
dv / dt < 10V / ns
IC - Amperes
VCE - Volts

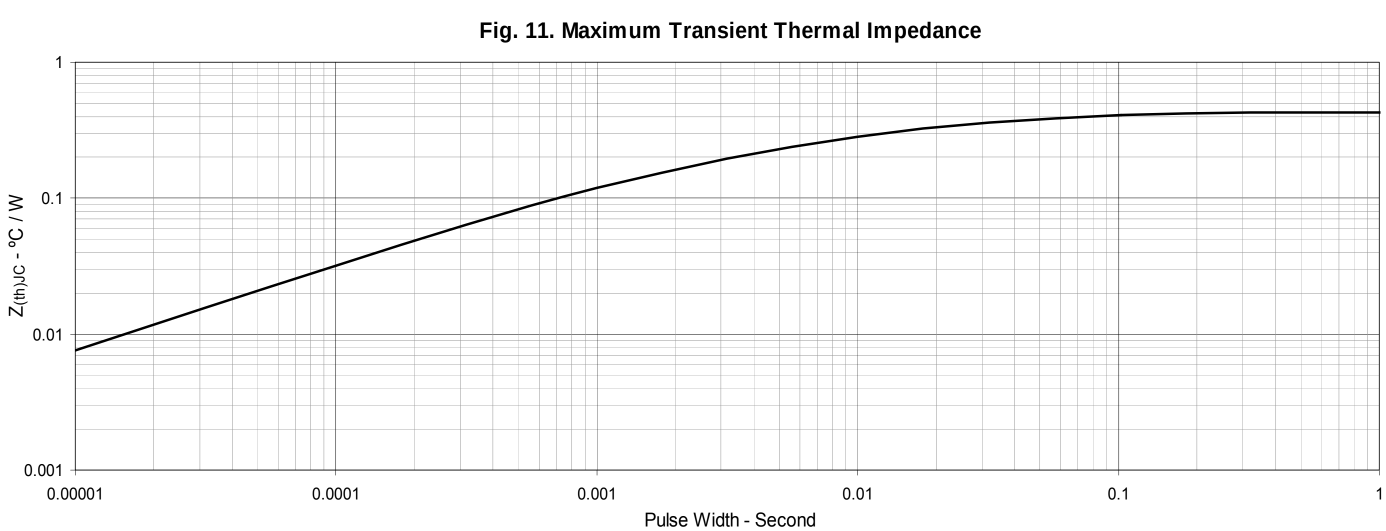


Fig. 11. Maximum Transient Thermal Impedance
Z(th)JC - ºC / W
Pulse Width - Second

Fig. 12. Inductive Switching Energy Loss vs. Gate Resistance

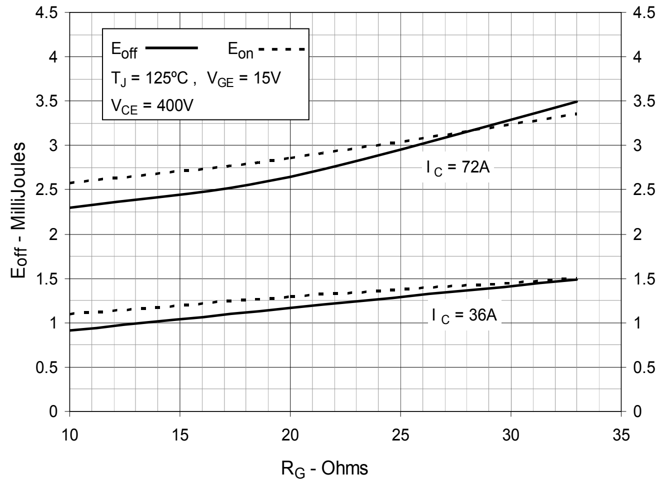


Fig. 13. Inductive Switching Energy Loss vs. Collector Current

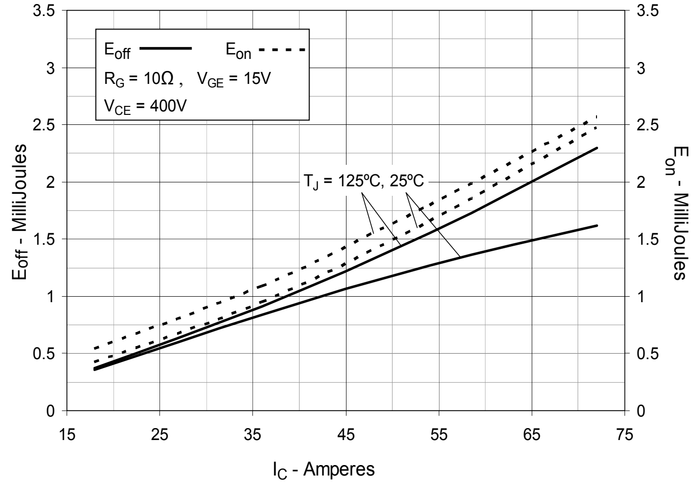


Fig. 14. Inductive Switching Energy Loss vs. Junction Temperature

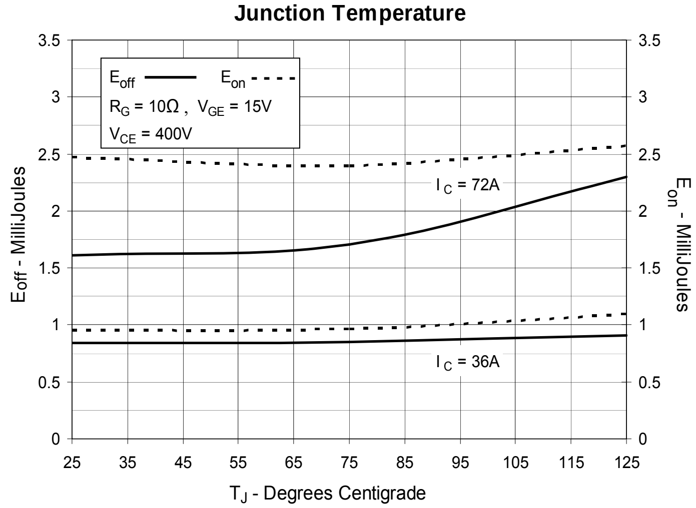


Fig. 15. Inductive Turn-off Switching Times vs. Gate Resistance

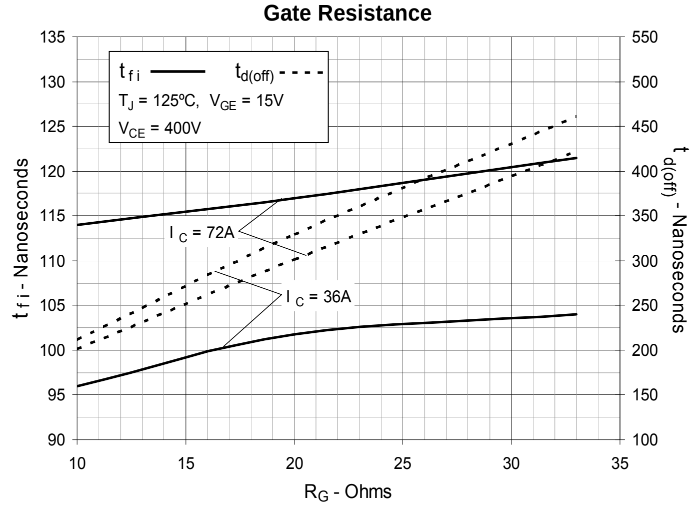


Fig. 16. Inductive Turn-off Switching Times vs. Collector Current

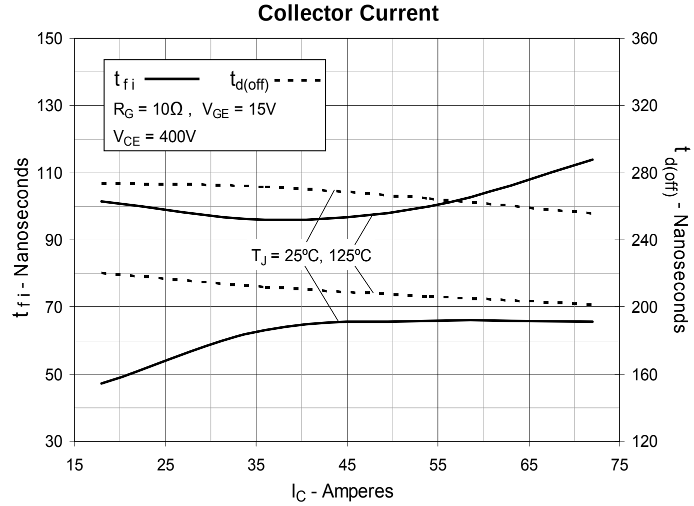


Fig. 17. Inductive Turn-off Switching Times vs. Junction Temperature

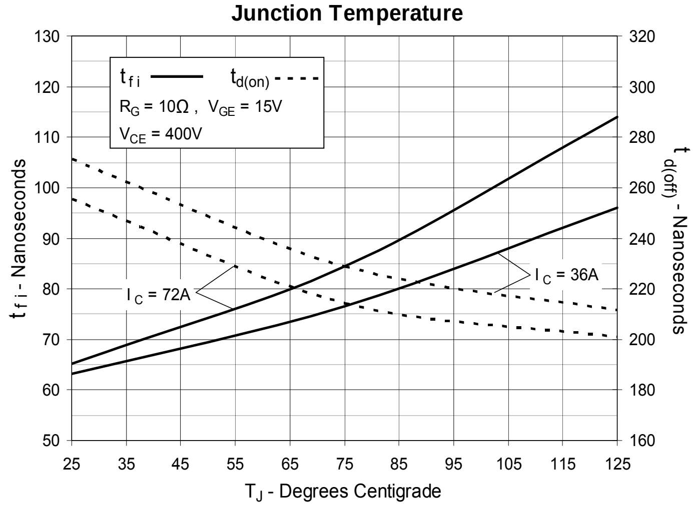


Fig. 18. Inductive Turn-on Switching Times vs. Gate Resistance

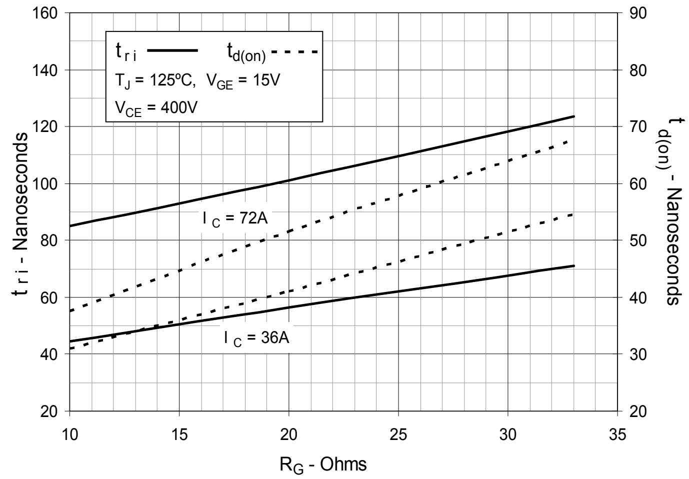


Fig. 19. Inductive Turn-on Switching Times vs. Collector Current

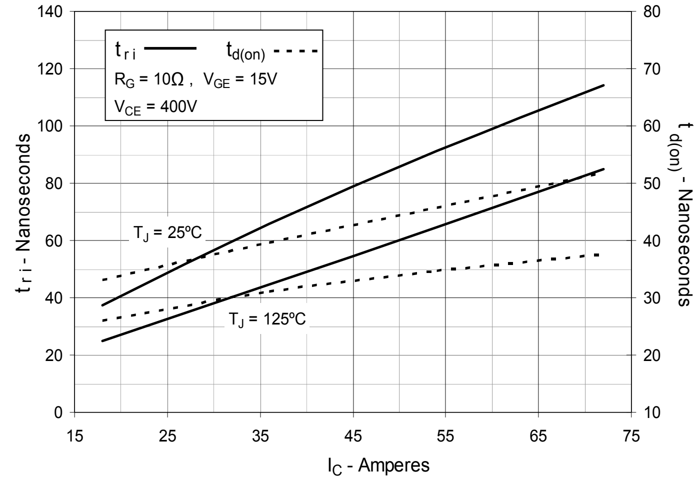


Fig. 20. Inductive Turn-on Switching Times vs. Junction Temperature